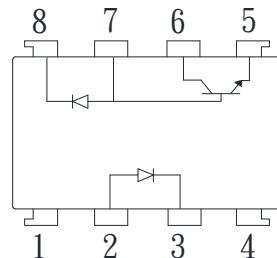


● Description

The KPC6N136 series consist of an LED optically coupled to an OPIC chip. It is a high-speed digital output type photocoupler designed specifically for low circuit current. And it is packaged in a 8 pin DIP package and available in wide-lead spacing and SMD option.

● Schematic



- | | |
|------------|-------------------|
| 1. N.C. | 5. GND |
| 2. Anode | 6. Vo |
| 3. Cathode | 7. V _B |
| 4. N.C. | 8. Vcc |

● Features

1. Pb free and RoHS compliant
2. High speed response t_{PHL}, t_{PLH} (Max. 0.8us at $R_L=1.9K\Omega$)
3. High common mode rejection voltage (CM_H : TYP. 1KV/us)
4. Standard dual-in-line package
5. MSL class 1
6. Agency Approvals:
 - UL Approved (No. E169586): UL1577
 - c-UL Approved (No. E169586)
 - FIMKO Approved: EN62368-1, EN60601-1
 - VDE Approved (No. 40020973): DIN EN60747-5-5

● Applications

- Computers, measuring instruments, control equipment
- High speed line receivers, high speed logic
- Telephone sets
- Signal transmission between circuits of different potentials and impedances



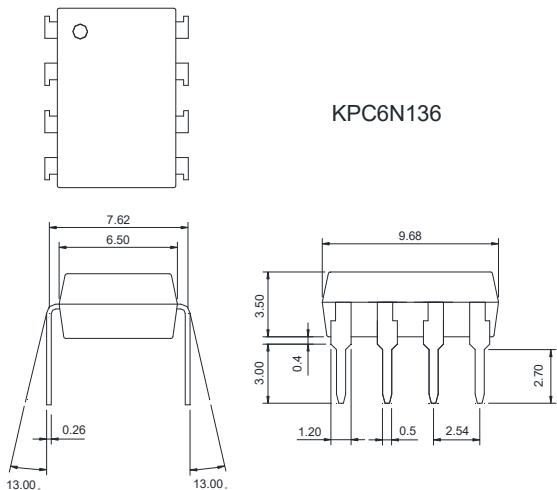
KPC6N136 Series

8PIN HIGH-SPEED OUTPUT PHOTOCOUPLER

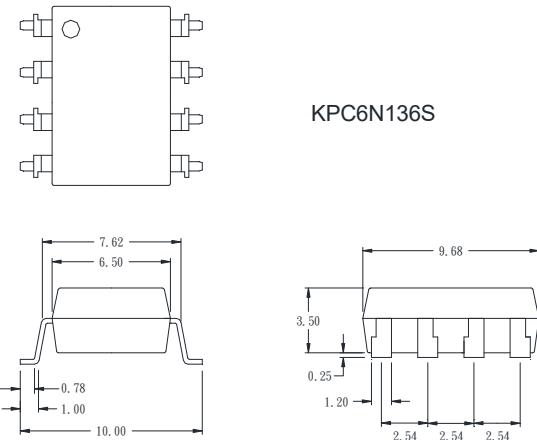
● Outside Dimension

Unit : mm

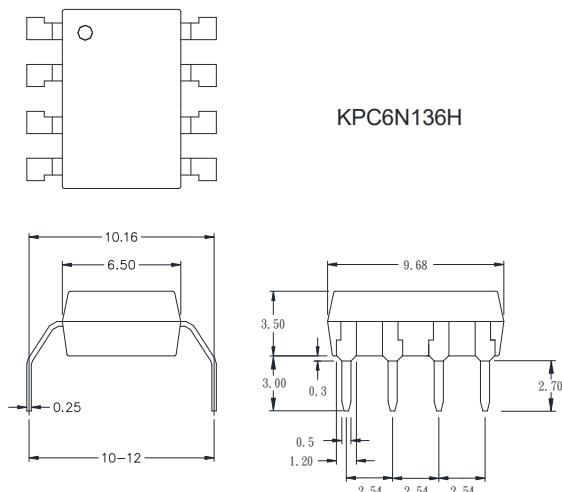
1.Dual-in-line type



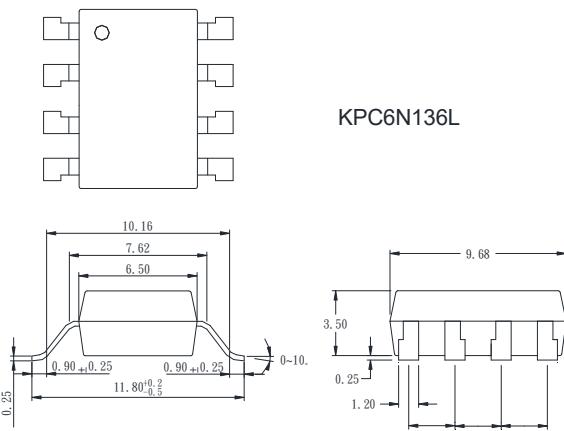
2.Surface mount type



3.Long creepage distance type

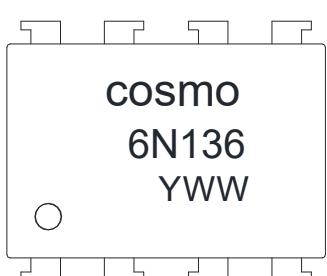


4.Long creepage distance
for surface mount type



TOLERANCE: ±0.2mm

● Device Marking



Notes:

cosmo
6N136
YWW

Y: Year code / WW: Week code



KPC6N136 Series

8PIN HIGH-SPEED OUTPUT
PHOTOCOUPLER

● Absolute Maximum Ratings

(Ta = 25°C)

Parameter	Symbol	Rating	Unit
Input	Forward current	I _F	25 mA
	*1 Peak forward current	I _F	50 mA
	*2 Peak transient forward current	I _{FM}	1 A
	Reverse voltage	V _R	5 V
	Power dissipation	P	45 mW
Output	Supply voltage	V _{CC}	-0.5 to 15 V
	Output voltage	V _O	-0.5 to 15 V
	Emitter-base reverse with stand voltage (Pin5 to 7)	V _{EBO}	5 V
	Average output current	I _O	8 mA
	Peak output current	I _{OP}	16 mA
	Base current (Pin7)	I _B	5 mA
	Power dissipation	P _O	100 mW
	*3 Isolation voltage 1 minute	V _{iso}	5000 V
	Operating temperature	T _{opr}	-55 to +100 °C
Storage temperature		T _{stg}	-55 to +125 °C
*4 Soldering temperature 10 seconds		T _{sol}	260 °C

*1 50% duty cycle, Pulse width : 1mS

Decreases at the rate of 1.6mA/°C if the external temperature is 70°C or more.

*2 Pulse width \leq 1uS, 300pulse/sec

*3 40 to 60% RH, AC for 1 minute

*4 For 10 seconds

● Electrical Characteristics

(Ta = 25°C)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
*5 Current transfer ratio	CTR(1)	Ta=25°C, I _F =16mA V _O =0.4V, V _{CC} =4.5V	19	40	-	%
	CTR(2)	I _F =16mA V _O =0.5V, V _{CC} =4.5V	15	43	-	%
Logic (0) output voltage	V _{OL}	*6 V _{CC} =4.5V, I _F =16mA	-	0.1	0.4	V
Logic (1) output current	I _{OH(1)}	Ta=25°C, I _F =0 V _O =V _{CC} =5.5V	-	3.0	500	nA
	I _{OH(2)}	Ta=25°C, I _F =0 V _O =V _{CC} =15V	-	0.01	1.0	uA
	I _{OH(3)}	V _{CC} =V _O =15V, I _F =0	-	-	50	uA
Logic (0) supply current	I _{CCL}	I _F =16mA V _O =open, V _{CC} =15V	-	200	-	uA
Logic (1) supply current	I _{CCH(1)}	Ta=25°C, I _O =0 V _F =open, V _{CC} =15V	-	0.02	1.0	uA
	I _{CCH(2)}	I _O =0 V _O =open, V _{CC} =15V	-	-	2.0	uA
Input forward voltage	V _F	Ta=25°C, I _F =16mA	-	1.7	1.95	V
Input forward voltage temperature coefficient	△ V _F /△ Ta	I _F =16mA	-	-1.9	-	mV/°C
Input reverse voltage	BV _R	Ta=25°C, I _R =10uA	5.0	-	-	V
Input capacitance	C _{IN}	V _F =0, f=1MHz	-	60	-	pF
*7 Leak current (input-output)	I _{I-O}	Ta=25°C, 45%RH V _{I-O} =3KVDC, t=5s	-	-	1.0	uA
*7 Isolation resistance (input-output)	R _{I-O}	V _{I-O} =500VDC	-	10 ¹²	-	Ω
*7 Capacitance (input-output)	C _{I-O}	f=1MHz	-	0.6	-	pF
Transistor current amplification factor	h _{FE}	V _O =5V, I _O =3mA	-	70	-	

*5 Current transfer ratio is the ratio of input current and output current expressed in %

*6 I_O=2.4mA

*7 Measured as 2-pin element (Short 1, 2, 3, 4 and 5, 6, 7, 8)

● Switching Characteristics
 $(Ta=25^\circ\text{C}, V_{CC}=5\text{V}, I_F=16\text{mA} \text{ Ta} = 25^\circ\text{C})$

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
*8 Propagation delay time *9 Output (1) → (0)	t_{PHL}	$R_L=1.9\text{K}\Omega$	-	0.3	0.8	μs
*8 Propagation delay time *9 Output (0) → (1)	t_{PLH}	$R_L=1.9\text{K}\Omega$	-	0.3	0.8	μs
*10 Instantaneous common mode rejection voltage *11 "Output (1)"	CM_H	$I_F=0, V_{CM}=10\text{V}_{P-P}$	-	1000	-	$\text{V}/\mu\text{s}$
*10 Instantaneous common mode rejection voltage *11 "Output (0)"	CM_L	$I_F=16\text{mA}, V_{CM}=10\text{V}_{P-P}$	-	-1000	-	$\text{V}/\mu\text{s}$
*12 Bandwidth	BW	$R_L=100\Omega$	-	2.0	-	MHz

*8 $R_L=1.9\text{K}\Omega$ is equivalent to one LSTTL and 5.6KΩ pull-up resistor.

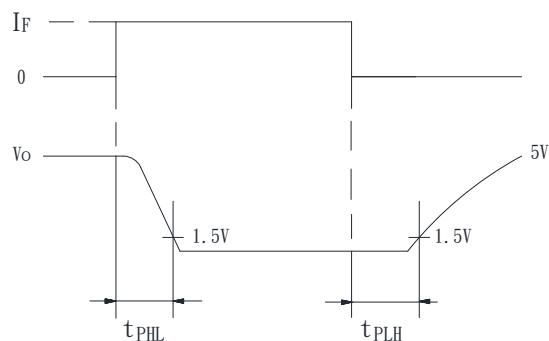
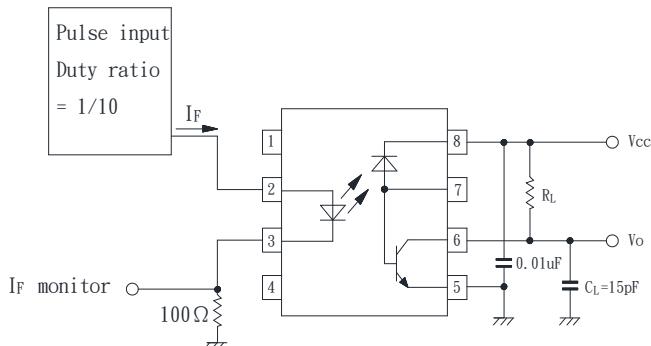
*10 Instantaneous common mode rejection voltage "output (1)" represents a common mode voltage variation that can hold the output above (1) level ($V_o > 2.0\text{V}$)

Instantaneous common mode rejection voltage "output (0)" represents

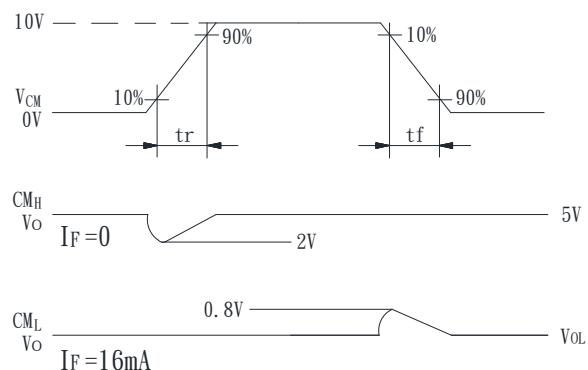
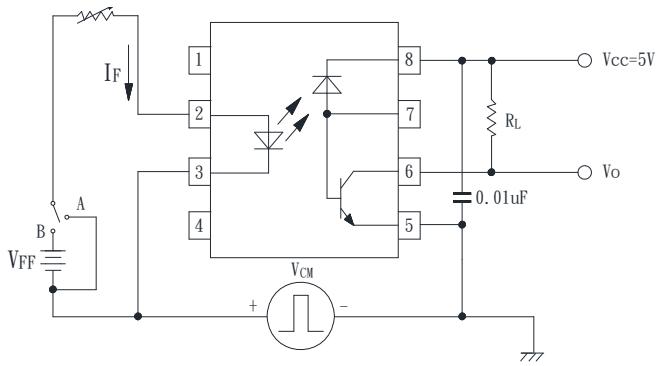
a common mode voltage variation that can hold the output above (0) level ($V_o < 0.8\text{V}$)

*12 Bandwidth represents a point where AC input goes down by 3dB.

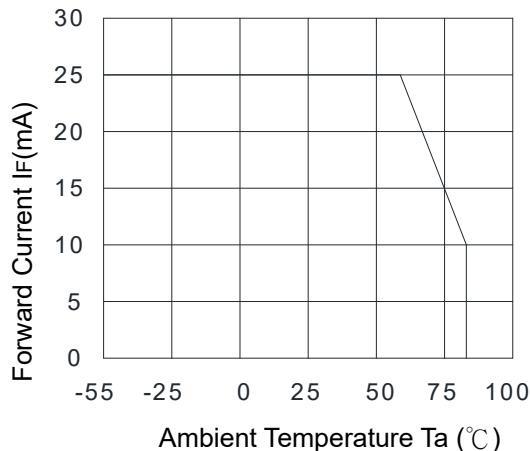
*9 Test Circuit Propagation Delay Time



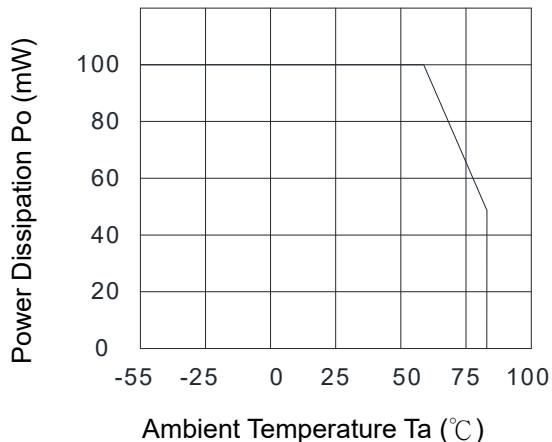
*11 Test Circuit for Instantaneous Common Mode Rejection Voltage



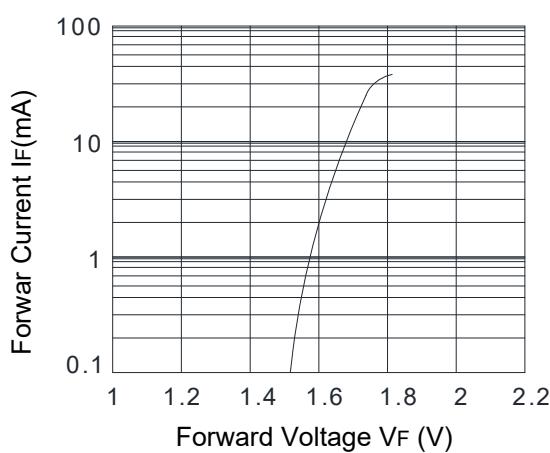
**Fig.1 Forward Current
vs. Ambient Temperature**



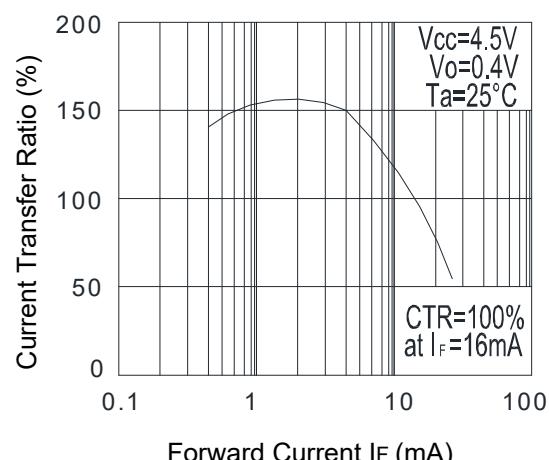
**Fig.2 Power Dissipation
vs. Ambient Temperature**



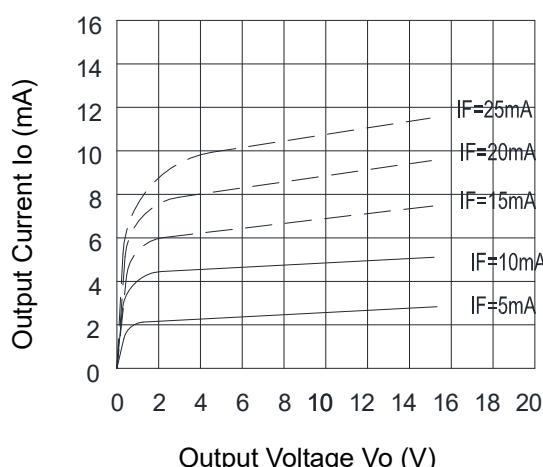
**Fig.3 Forward Current
vs. Forward Voltage**



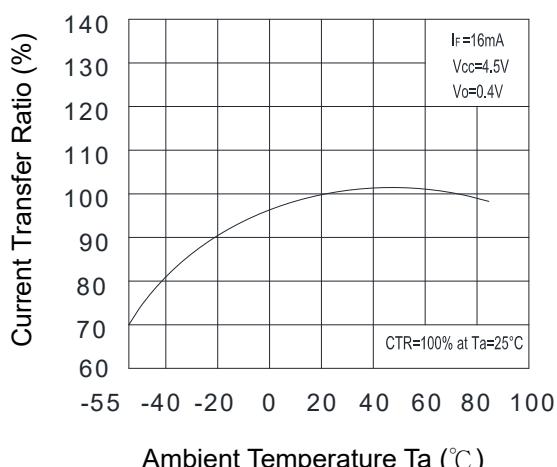
**Fig.4 Current Transfer Ratio
vs. Forward Current**



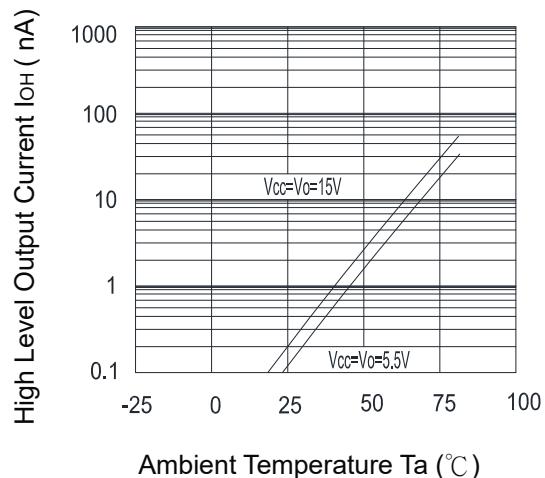
**Fig.5 Output Current
vs. Output Voltage**



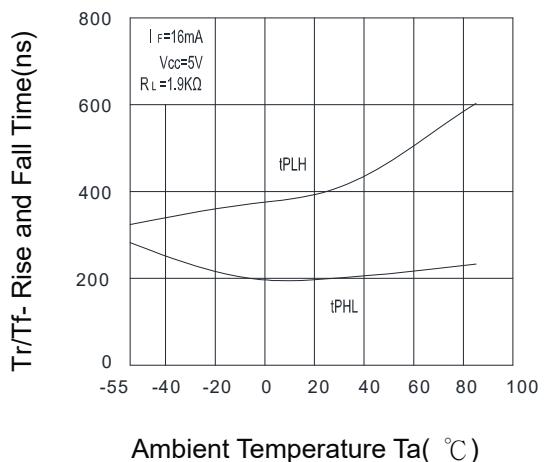
**Fig.6 Current Transfer Ratio
vs. Ambient Temperature**



**Fig.7 High Level Output Current
vs. Ambient Temperature**



**Fig.8 Propagation Delay Time
vs. Ambient Temperature**

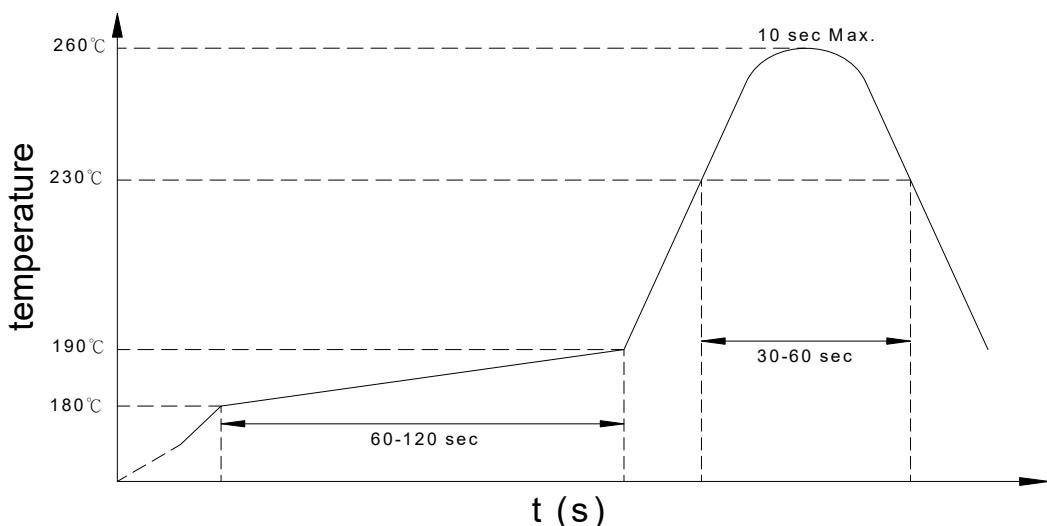


- Recommended Soldering Conditions

- (a) Infrared reflow soldering :

- | | |
|--|--|
| ■ Peak reflow soldering : | 260°C or below (package surface temperature) |
| ■ Time of peak reflow temperature : | 10 sec |
| ■ Time of temperature higher than 230°C : | 30-60 sec |
| ■ Time to preheat temperature from 180~190°C : | 60-120 sec |
| ■ Time(s) of reflow : | Two |
| ■ Flux : | Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.) |

Recommended Temperature Profile of Infrared Reflow



- (b) Wave soldering :

- | | |
|---------------------------|--|
| ■ Temperature : | 260°C or below (molten solder temperature) |
| ■ Time : | 10 seconds or less |
| ■ Preheating conditions : | 120°C or below (package surface temperature) |
| ■ Time(s) of reflow : | One |
| ■ Flux : | Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.) |

- (c) Cautions :

- Fluxes : Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.
- Avoid shorting between portion of frame and leads.

- Numbering System

KPC6N136 X (Y)

Notes:

KPC6N135 = Part No.

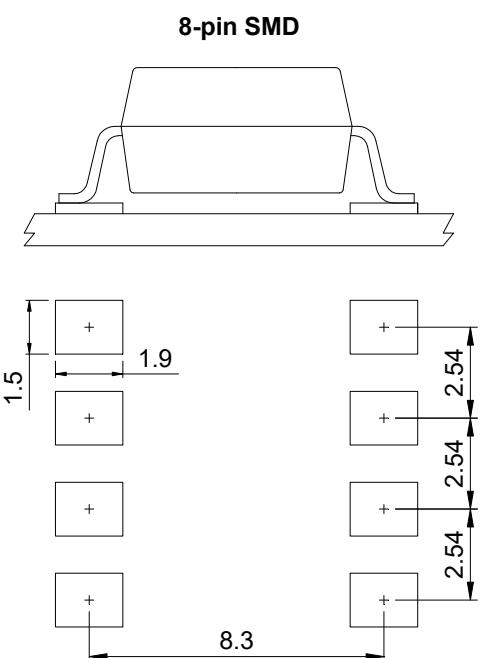
X = Lead form option (blank、S、H、L)

Y = Tape and reel option (TL、TR、TLD、TRU)

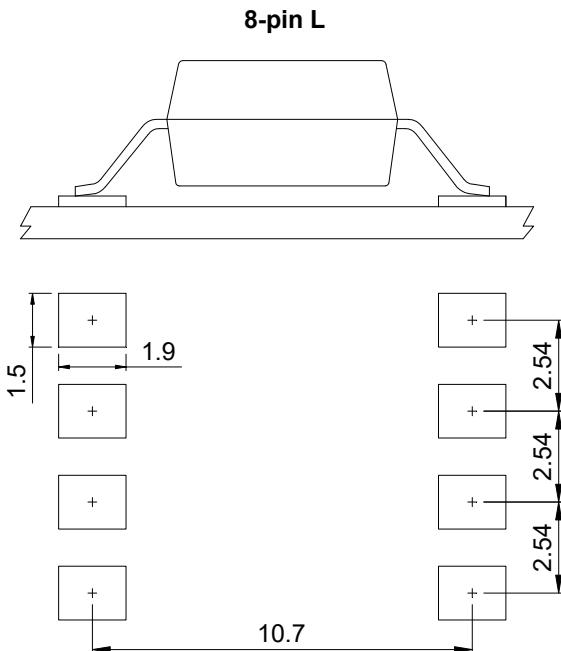
Option	Description	Packing quantity
S (TL)	surface mount type package + TL tape & reel option	1000 units per reel
S (TR)	surface mount type package + TR tape & reel option	1000 units per reel
L (TLD)	long creepage distance for surface mount type package + TLD tape & reel option	800 units per reel
L (TRU)	long creepage distance for surface mount type package + TRU tape & reel option	800 units per reel

- Recommended Pad Layout for Surface Mount Lead Form

1.Surface mount type

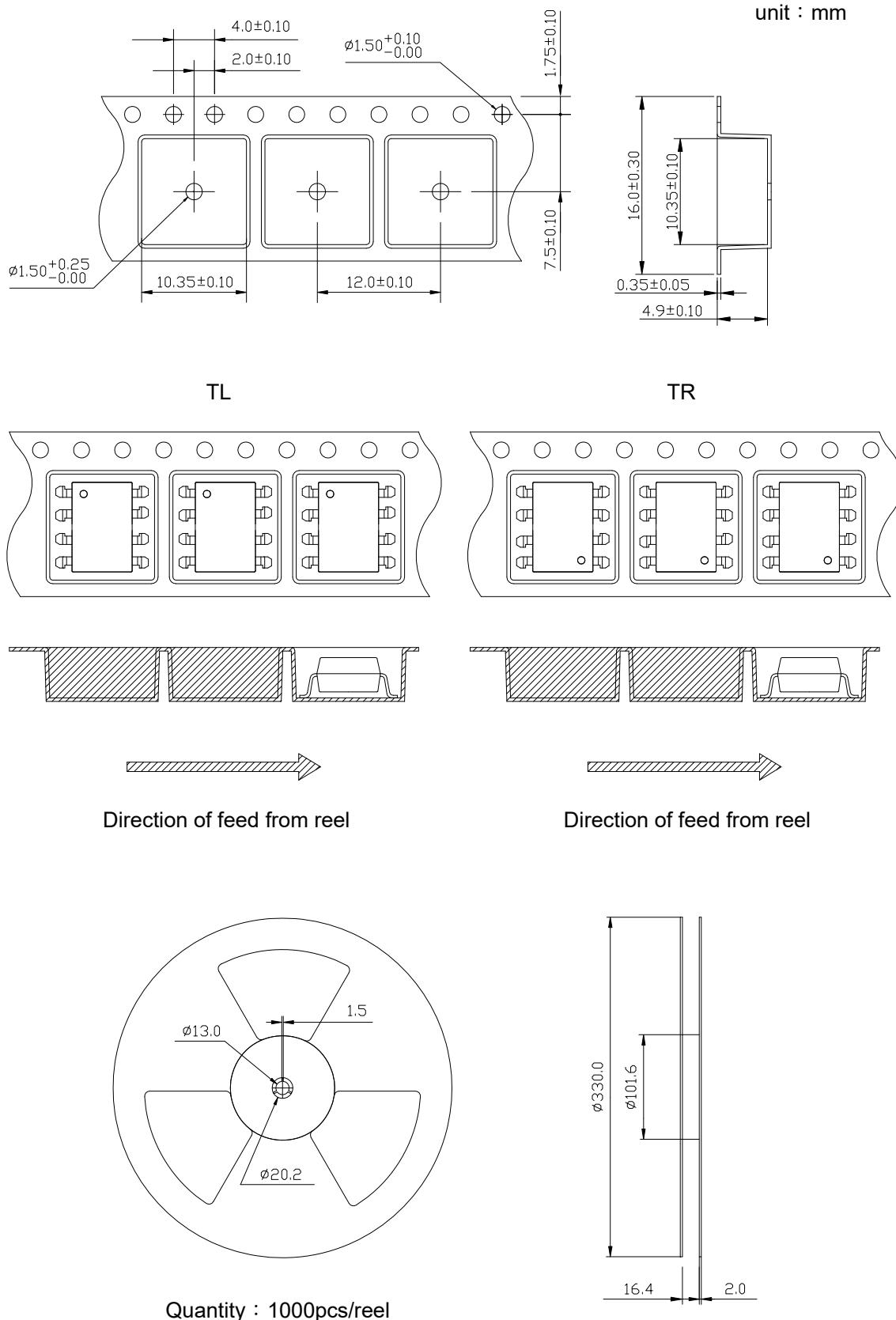


2.Long creepage distance for surface mount type

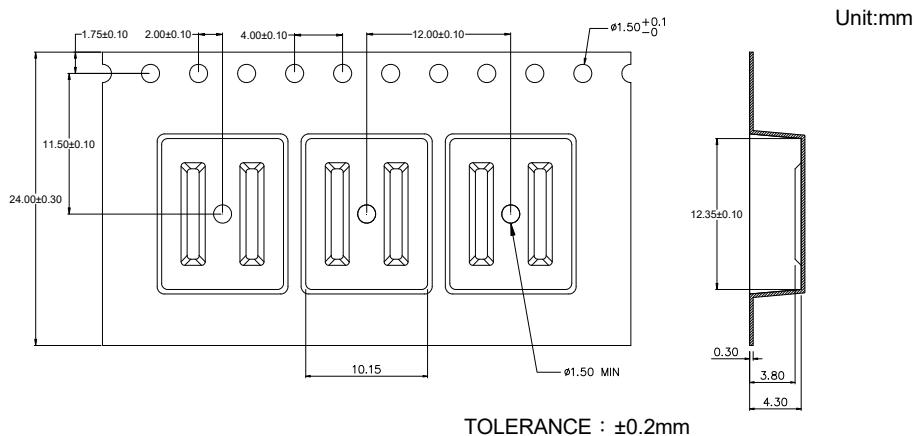


Unit :mm

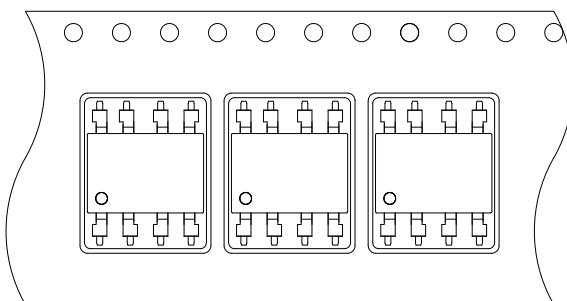
- 8-pin SMD Carrier Tape & Reel



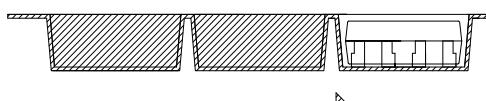
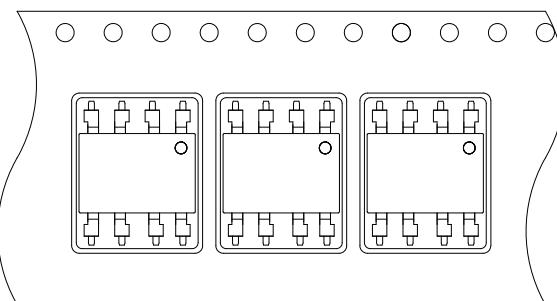
- 8-pin L Carrier Tape & Reel



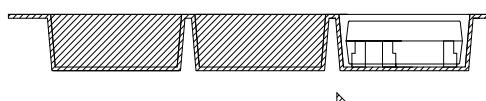
TLD



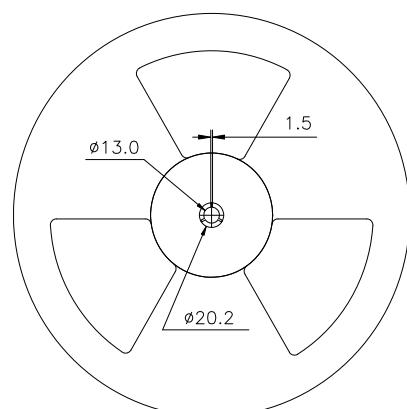
TRU



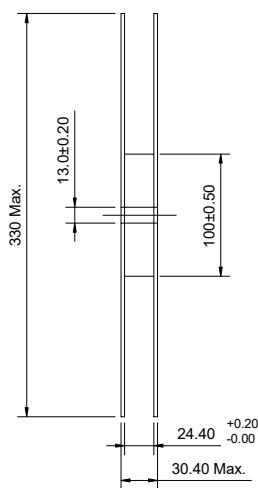
Direction of feed from reel



Direction of feed from reel



Quantity : 800pcs/reel



● Application Notice

The statements regarding the suitability of products for certain types of applications are based on cosmo's knowledge of general applications of cosmo products. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to verify the specifications are suitable for use in a particular application. Customers are solely responsible for all aspects of their own product design or applications. The parameters provided in the datasheet may vary in different applications and performance may vary over time. All operating parameters (including typical parameters) must be validated by customer's technical experts for different applications. cosmo assumes no liability for customer' product design or applications. Product specifications do not expand or otherwise change cosmo's terms and conditions of purchase, including but not limited to the warranty expressed therein.

When using cosmo products, please comply with safety standards and instructions. cosmo has no liability and responsibility to the damage caused by improper use of the instructions specified in the specifications.

cosmo products are designed for use in general electronic equipment such as telecommunications, office automation equipment, personal computers, test and measurement equipment, consumer electronics, industrial control, instrumentation, audio, video.

cosmo devices shall not be used in equipment that requires higher level of reliability and safety, such as nuclear power control equipment, telecommunication equipment(trunk lines), space application, medical and other life supporting equipment, and equipment for aircraft, military, automotive or any other application that can cause human injury or death.

cosmo reserves the right to change the specifications, data, characteristics, structure, materials and other contents at any time without notice. Please contact cosmo to obtain the latest specification.

cosmo disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.